

# CD4510B, CD4516B Types

## CMOS Presettable Up/Down Counters

High-Voltage Types (20-Volt Rating)

CD4510B — — — BCD Type

CD4516B — — — Binary Type

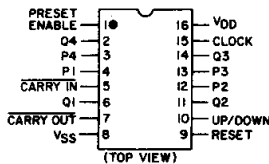
■ CD4510B Presettable BCD Up/Down Counter and the CD4516 Presettable Binary Up/Down Counter consist of four synchronously clocked D-type flip-flops (with a gating structure to provide T-type flip-flop capability) connected as counters. These counters can be cleared by a high level on the RESET line, and can be preset to any binary number present on the jam inputs by a high level on the PRESET ENABLE line. The CD4510B will count out of non-BCD counter states in a maximum of two clock pulses in the up mode, and a maximum of four clock pulses in the down mode.

If the CARRY-IN input is held low, the counter advances up or down on each positive-going clock transition. Synchronous cascading is accomplished by connecting all clock inputs in parallel and connecting the CARRY-OUT of a less significant stage to the CARRY-IN of a more significant stage.

The CD4510B and CD4516B can be cascaded in the ripple mode by connecting the CARRY-OUT to the clock of the next stage. If the UP/DOWN input changes during a terminal count, the CARRY-OUT must be gated with the clock, and the UP/DOWN input must change while the clock is high. This method provides a clean clock signal to the subsequent counting stage. (See Fig. 15).

These devices are similar to types MC14510 and MC14516.

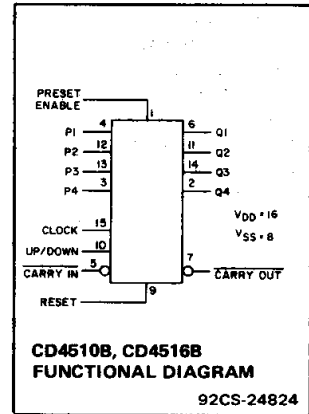
The CD4510B and CD4516B types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes). The CD4516B types also are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix).



92CS-27015  
**CD4510B, CD4516B**  
TERMINAL ASSIGNMENT

### Features:

- Medium-speed operation --  
 $f_{CL} = 8 \text{ MHz typ. at } 10 \text{ V}$
- Synchronous internal carry propagation
- Reset and Preset capability
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Standardized symmetrical output characteristics
- Maximum input current of  $1 \mu\text{A}$  at 18 V over full package temperature range; 100 nA at 18 V and  $25^\circ\text{C}$
- Noise margin (full package-temperature range):  
1 V at  $V_{DD} = 5 \text{ V}$   
2 V at  $V_{DD} = 10 \text{ V}$   
2.5 V at  $V_{DD} = 15 \text{ V}$
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



### Applications:

- Up/Down difference counting
- Multistage synchronous counting
- Multistage ripple counting
- Synchronous frequency dividers

### OPERATING CONDITIONS AT $T_A = 25^\circ\text{C}$ , Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges.

Characteristic	$V_{DD}$	Min.	Max.	Units
Supply Voltage Range (At $T_A = \text{Full Package-Temperature Range}$ )		3	18	V
Clock Pulse Width, $t_W$	5	150	—	ns
	10	75	—	
	15	60	—	
Clock Input Frequency, $f_{CL}$	5	—	2	MHz
	10	—	4	
	15	—	5.5	
Preset Enable or Reset Removal Time <sup>●</sup>	5	150	—	ns
	10	80	—	
	15	60	—	
Clock Rise and Fall Time, $t_{rCL}$ , $t_{fCL}$ <sup>*</sup>	5	—	15	$\mu\text{s}$
	10	—	5	
	15	—	5	
Carry-In Setup Time, $t_S$	5	130	—	ns
	10	60	—	
	15	45	—	
Up-Down Setup Time, $t_S$	5	360	—	ns
	10	160	—	
	15	110	—	
Preset Enable or Reset Pulse Width, $t_W$	5	220	—	ns
	10	100	—	
	15	75	—	

<sup>●</sup>Time required after the falling edge of the reset or preset enable inputs before the rising edge of the clock will trigger the counter (similar to setup time).

<sup>\*</sup>If more than one unit is cascaded in the parallel clocked application,  $t_{rCL}$  should be made less than or equal to the sum of the fixed propagation delay at 15 pF and the transition time of the carry output driving stage for the estimated capacitive load.

# CD4510B Types

## MAXIMUM RATINGS, Absolute-Maximum Values:

<b>DC SUPPLY-VOLTAGE RANGE, (V<sub>DD</sub>)</b>	
Voltages referenced to V <sub>SS</sub> Terminal	-0.5V to +20V
<b>INPUT VOLTAGE RANGE, ALL INPUTS</b>	-0.5V to V <sub>DD</sub> +0.5V
<b>DC INPUT CURRENT, ANY ONE INPUT</b>	±10mA
<b>POWER DISSIPATION PER PACKAGE (P<sub>D</sub>):</b>	
For T <sub>A</sub> = -55°C to +100°C	500mW
For T <sub>A</sub> = +100°C to +125°C	Derate Linearity at 12mW/°C to 200mW
<b>DEVICE DISSIPATION PER OUTPUT TRANSISTOR</b>	
FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	100mW
<b>OPERATING-TEMPERATURE RANGE (T<sub>A</sub>)</b>	-55°C to +125°C
<b>STORAGE TEMPERATURE RANGE (T<sub>stg</sub>)</b>	-65°C to +150°C
<b>LEAD TEMPERATURE (DURING SOLDERING):</b>	
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max	+265°C

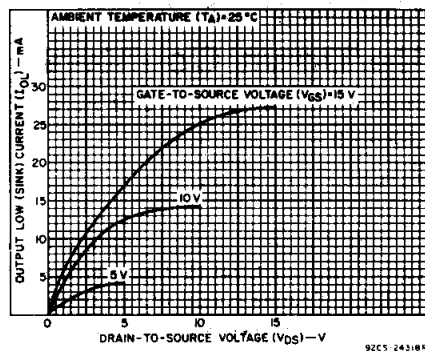


Fig. 1 - Typical output low (sink) current characteristics.

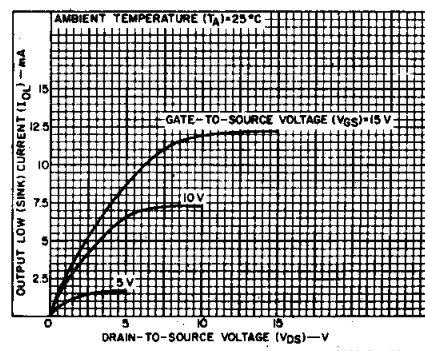


Fig. 2 - Minimum output low (sink) current characteristics.

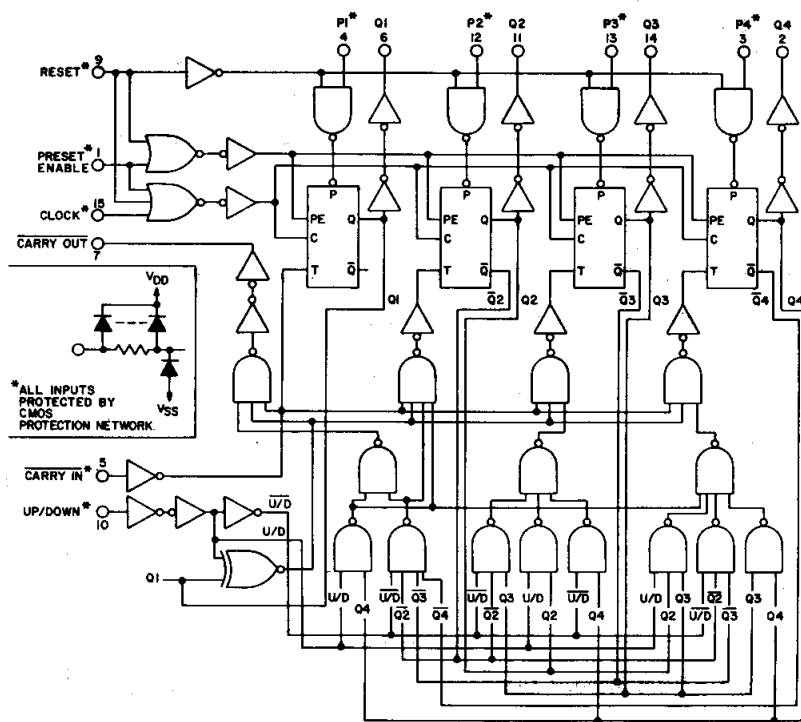


Fig. 3 - Logic Diagram for CD4510B.

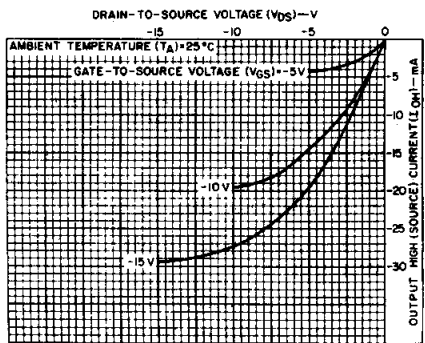


Fig. 4 - Typical output high (source) current characteristics.

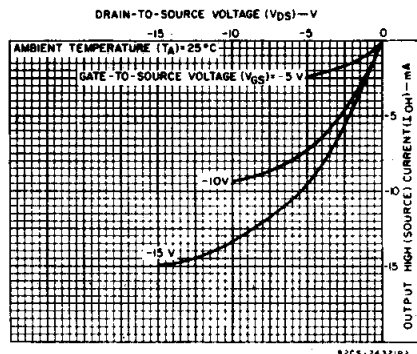


Fig. 5 - Minimum output high (source) current characteristics.

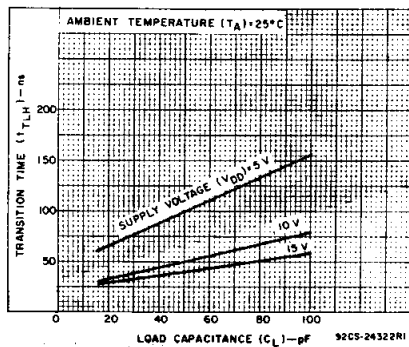


Fig. 6 - Typical transition time vs. load capacitance.

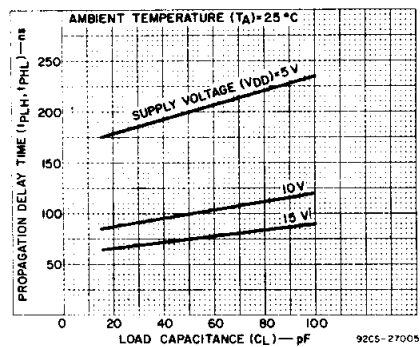


Fig. 7 - Typical propagation delay time vs. load capacitance for clock-to-Q outputs.

# CD4510B Types

## STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I <sub>DD</sub> Max.	-	0,5	5	5	5	150	150	-	0,04	5	μA
	-	0,10	10	10	10	300	300	-	0,04	10	
	-	0,15	15	20	20	600	600	-	0,04	20	
	-	0,20	20	100	100	3000	3000	-	0,08	100	
Output Low (Sink) Current I <sub>OL</sub> Min.	0,4	0,5	5	0,64	0,61	0,42	0,36	0,51	1	-	mA
	0,5	0,10	10	1,6	1,5	1,1	0,9	1,3	2,6	-	
	1,5	0,15	15	4,2	4	2,8	2,4	3,4	6,8	-	
Output High (Source) Current, I <sub>OH</sub> Min.	4,6	0,5	5	-0,64	-0,61	-0,42	-0,36	-0,51	-1	-	mA
	2,5	0,5	5	-2	-1,8	-1,3	-1,15	-1,6	-3,2	-	
	9,5	0,10	10	-1,6	-1,5	-1,1	-0,9	-1,3	-2,6	-	
Output Voltage: Low-Level, V <sub>OL</sub> Max.	-	0,5	5	0,05			-	0	0,05	-	V
	-	0,10	10	0,05			-	0	0,05	-	
	-	0,15	15	0,05			-	0	0,05	-	
Output Voltage: High-Level, V <sub>OH</sub> Min.	-	0,5	5	4,95			4,95	5	-	-	V
	-	0,10	10	9,95			9,95	10	-	-	
	-	0,15	15	14,95			14,95	15	-	-	
Input Low Voltage, V <sub>IL</sub> Max.	0,5, 4,5	-	5	1,5			-	-	1,5	-	V
	1, 9	-	10	3			-	-	3	-	
	1,5, 13,5	-	15	4			-	-	4	-	
Input High Voltage, V <sub>IH</sub> Min.	0,5, 4,5	-	5	3,5			3,5	-	-	-	V
	1, 9	-	10	7			7	-	-	-	
	1,5, 13,5	-	15	11			11	-	-	-	
Input Current I <sub>IN</sub> Max.	-	0,18	18	±0,1	±0,1	±1	±1	-	±10 <sup>-5</sup>	±0,1	μA

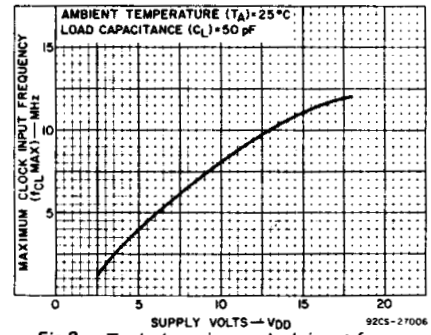


Fig. 8 - Typical maximum clock input frequency vs. supply voltage.

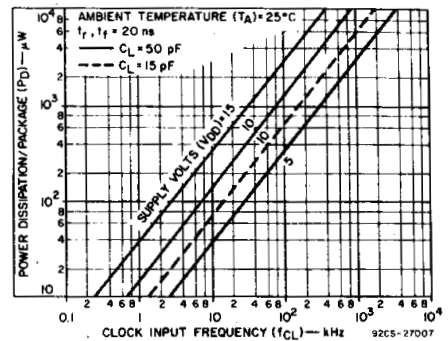


Fig. 9 - Typical dynamic power dissipation vs. frequency.

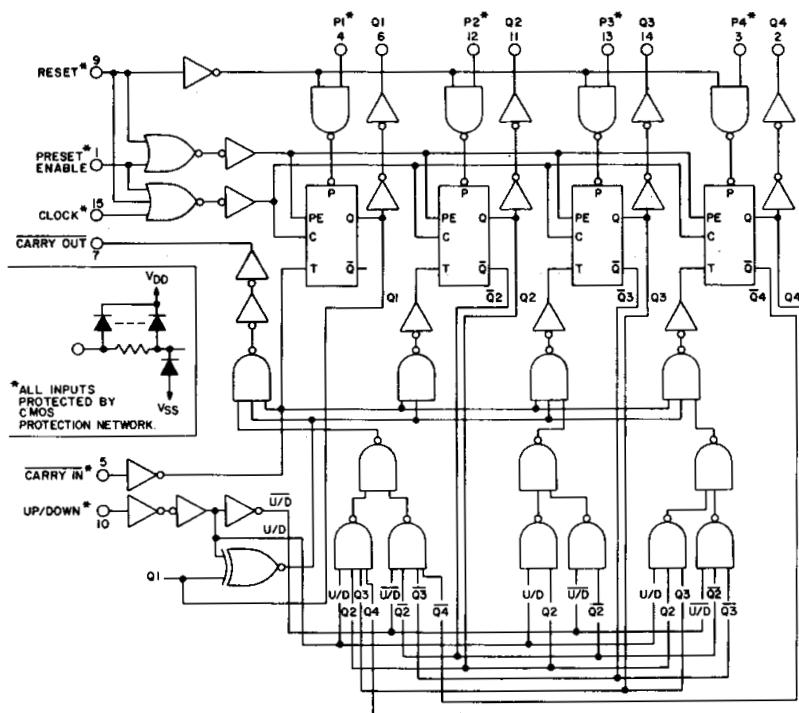


Fig. 10 - Logic Diagram for CD4516B.

92CS-27004R2

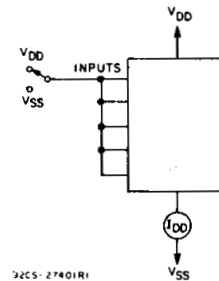


Fig. 11 - Quiescent-device-current test circuit.

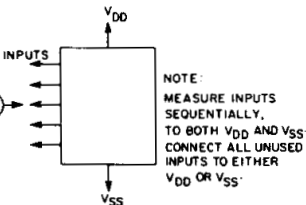


Fig. 12 - Input-current test circuit.

92CS-2740Z

3  
COMMERCIAL CMOS  
HIGH VOLTAGE ICs

## CD4510B Types

**DYNAMIC ELECTRICAL CHARACTERISTICS** at  $T_A = 25^\circ\text{C}$ ,  $C_L = 50\text{ pF}$ ,  
 Input  $t_r, t_f = 20\text{ ns}$ ,  $R_L = 200\text{ k}\Omega$

Characteristic	Conditions $V_{DD}$ (V)	Limits All Packages			Units
		Min.	Typ.	Max.	
Propagation Delay Time ( $t_{PHL}, t_{PLH}$ ): Clock-to-Q Output (See Fig. 10)	5	—	200	400	ns
	10	—	100	200	
	15	—	75	150	
Preset or Reset-to-Q Output	5	—	210	420	ns
	10	—	105	210	
	15	—	80	160	
Clock-to-Carry Out	5	—	240	480	ns
	10	—	120	240	
	15	—	90	180	
Carry-In-to-Carry Out	5	—	125	250	ns
	10	—	60	120	
	15	—	50	100	
Preset or Reset-to-Carry Out	5	—	320	640	ns
	10	—	160	320	
	15	—	125	250	
Transition Time ( $t_{THL}, t_{TLH}$ ) (See Fig. 9)	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Max. Clock Input Frequency ( $f_{CL}$ )	5	2	4	—	MHz
	10	4	8	—	
	15	5.5	11	—	
Input Capacitance ( $C_{IN}$ )		—	5	7.5	pF
Set-up Time, $t_S$ Preset Enable to $J_n$	5	25	12	—	ns
	10	10	6	—	
	15	10	5	—	
Hold times, $t_H$ Clock to Carry-In	5	60	30	—	ns
	10	30	4	—	
	15	30	1	—	
Clock to Up/Down	5	30	10	—	ns
	10	30	4	—	
	15	30	5	—	
Preset Enable to $J_n$	5	70	35	—	ns
	10	40	20	—	
	15	40	20	—	

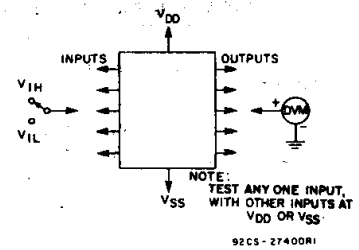


Fig. 13 - Input-voltage test circuit.

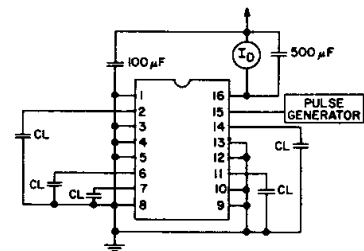


Fig. 14 - Power-dissipation test circuit and input waveform.

# CD4510B Types

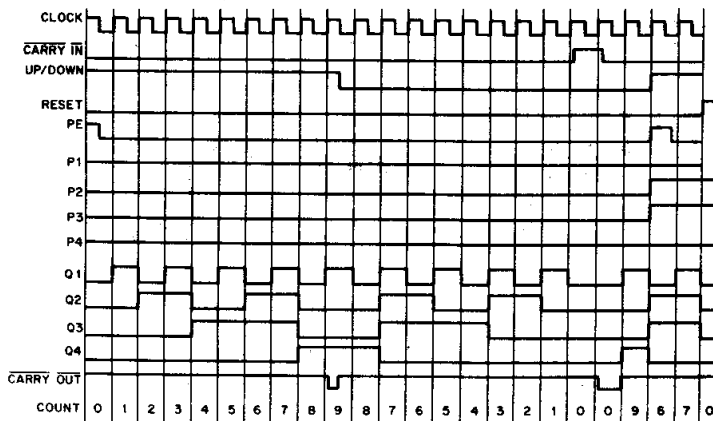


Fig. 15 — Timing Diagram for CD4510B.

92CM-2700B

CL	CI	U/D	PE	R	ACTION
X	1	X	0	0	NO COUNT
↓	0	1	0	0	COUNT UP
↓	0	0	0	0	COUNT DOWN
X	X	X	1	0	PRESET
X	X	X	X	1	RESET

X = DON'T CARE  
TRUTH TABLE

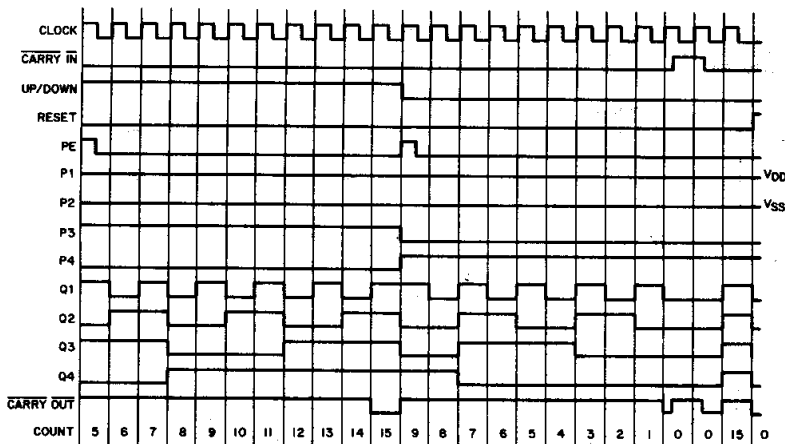
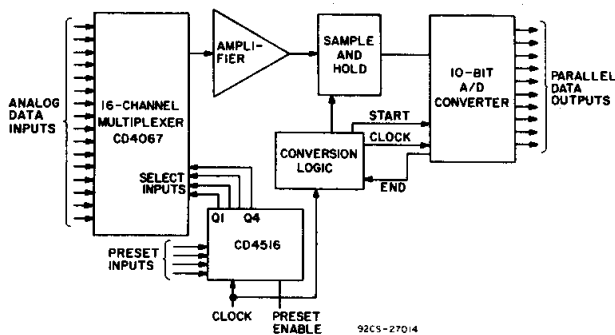


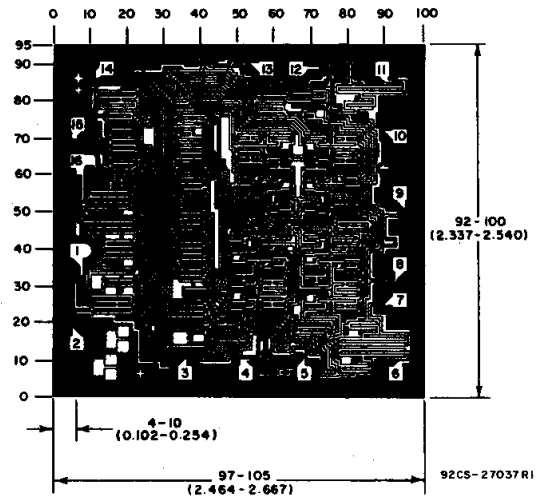
Fig. 16 — Timing diagram for CD4516B.

92CM-27009R1

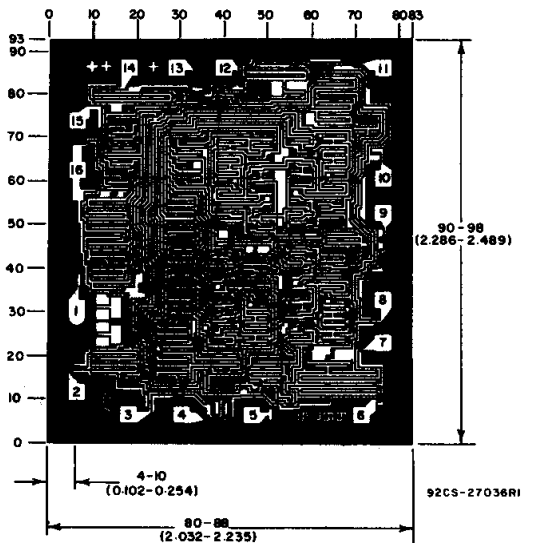


This acquisition system can be operated in the random access mode by jamming in the channel number at the preset inputs, or in the sequential mode by clocking the CD4516B.

Fig. 17 — Typical 16-channel, 10-bit data acquisition system.



Dimensions and Pad Layout for CD4510BH.

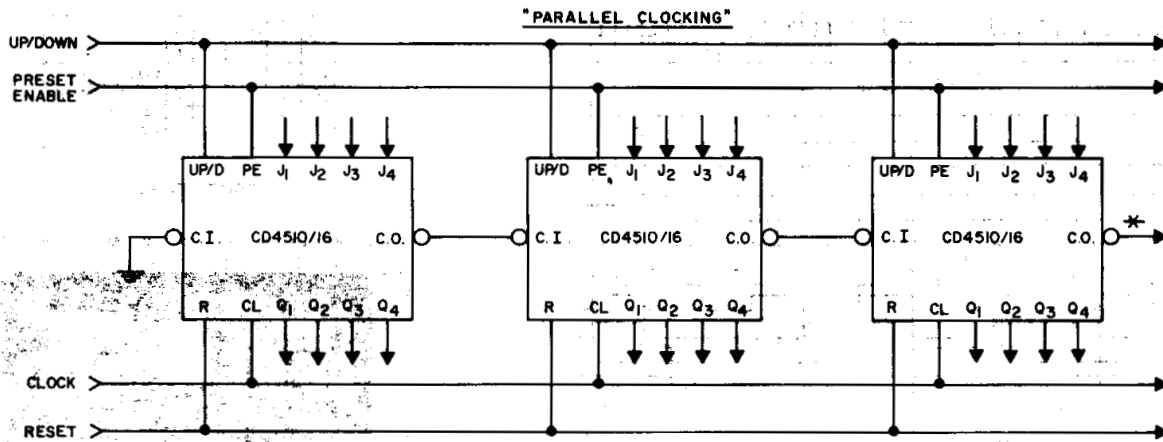


Dimensions and Pad Layout for CD4516BH.

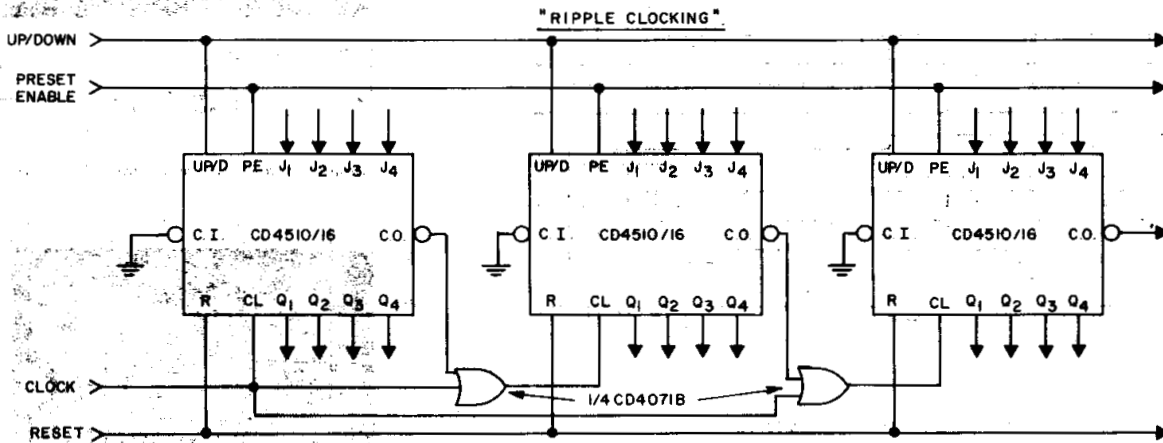
Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).

3  
COMMERCIAL CMOS  
HIGH VOLTAGE ICs

## CD4510B Types



\* **CARRY OUT** lines at the 2nd, 3rd, etc., stages may have a negative-going glitch pulse resulting from differential delays of different CD4510/16 IC's. These negative-going glitches do not affect proper CD4510/16 operation. However, if the **CARRY OUT** signals are used to trigger other edge-sensitive logic devices, such as FF's or counters, the **CARRY OUT** signals should be gated with the clock signal using a 2-input OR gate such as CD4071B.



**RIPPLE CLOCKING MODE:**  
THE UP/DOWN CONTROL CAN BE CHANGED AT ANY COUNT. THE ONLY RESTRICTION ON CHANGING THE UP/DOWN CONTROL IS THAT THE CLOCK INPUT TO THE FIRST COUNTING STAGE MUST BE "HIGH".

For cascading counters operating in a fixed up-count or down-count mode, the OR gates are not required between stages, and C.O. is connected directly to the CL input of the next stage with CI grounded.

92CL-17194R5

Fig. 18 — Cascading counter packages.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD4510BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4510BE	<a href="#">Samples</a>
CD4510BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4510BE	<a href="#">Samples</a>
CD4510BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4510B	<a href="#">Samples</a>
CD4510BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4510B	<a href="#">Samples</a>
CD4510BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM510B	<a href="#">Samples</a>
CD4516BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4516BE	<a href="#">Samples</a>
CD4516BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4516BE	<a href="#">Samples</a>
CD4516BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD4516BF	<a href="#">Samples</a>
CD4516BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD4516BF3A	<a href="#">Samples</a>
CD4516BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4516B	<a href="#">Samples</a>
CD4516BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM516B	<a href="#">Samples</a>
CD4516BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM516B	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF CD4516B, CD4516B-MIL :**

- Catalog: [CD4516B](#)
- Military: [CD4516B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications



**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4510BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4510BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD4516BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4516BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4510BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4510BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0
CD4516BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4516BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

PW (R-PDSO-G16)

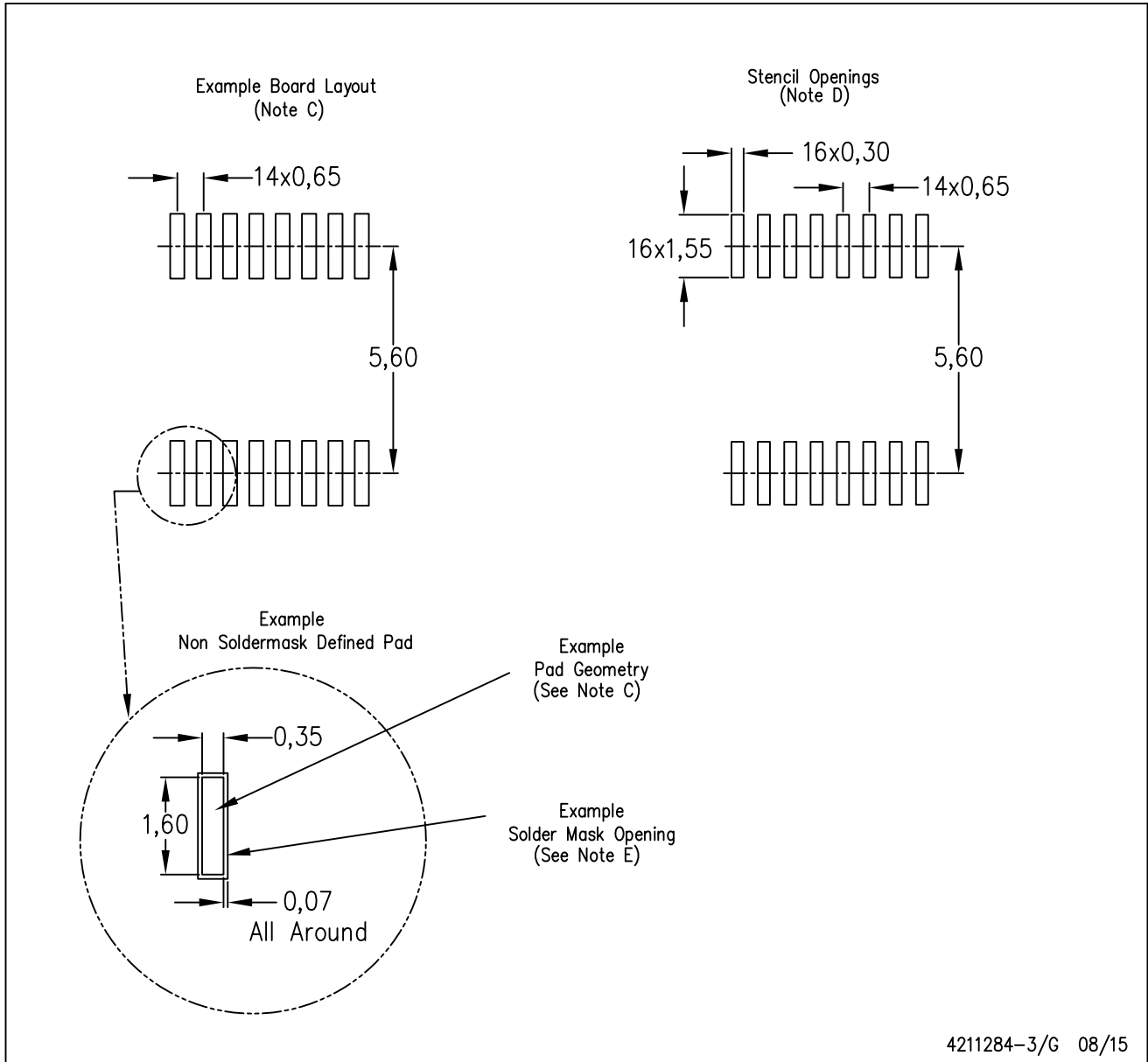
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)